

PD955 PY

SMT Adhesive

Description

PD955 PY is a thermosetting single component, solvent-free polymer adhesive, developed especially for the surface mounting of SMT components onto PCBs and for use on bare substrates. This rheology is specially adapted for printing application with metal and pump print-stencil.

Key Features

- Excellent adhesion with standard and also with difficult to glue components
- Very high green strength prevents component movement during placement
- Ideal, high dot form and excellent consistency of the glue dots

Physical Properties

Processing time at 20 – 30°C (days)	Max. 2
Curing Profile	The standard curing conditions are 125°C / 3 minutes. As long as the curing profile is respected, the adhesive can withstand reflow conditions according IPC/JEDEC J-STD-020 1 min / 180 °C 1,5 min / 150 °C 3 min / 125 °C 8 min / 100 °C
Color	Yellow
Applications	Printing Pin Transfer



**This picture is solely intended for illustration purposes. Syringes and jars are available in different types and colors and may change over time.*

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Adhesive Conditioning

- Remove adhesive from fridge: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open cartridge while adhesive is cold to prevent condensation

Cleaning Instructions

Before curing: The adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. Do not use alcohol as this will cure the adhesive. Cleaned dispensing units should be completely dried before installation.

After Curing: Defective components can be replaced by heating (with hot air) the cured adhesive joint above 100 °C. After removing the component (torsion movement), the hot air should be focused on the remaining adhesive in order to remove it with a sharp tool.

Storage Conditions

- Store the SMT-adhesive in originally sealed containers and avoid exposure to high humidity and sunlight
- Store cartridges with tip pointing downwards
- Max. expiration date: Shelf life: Please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 – 10 °C

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